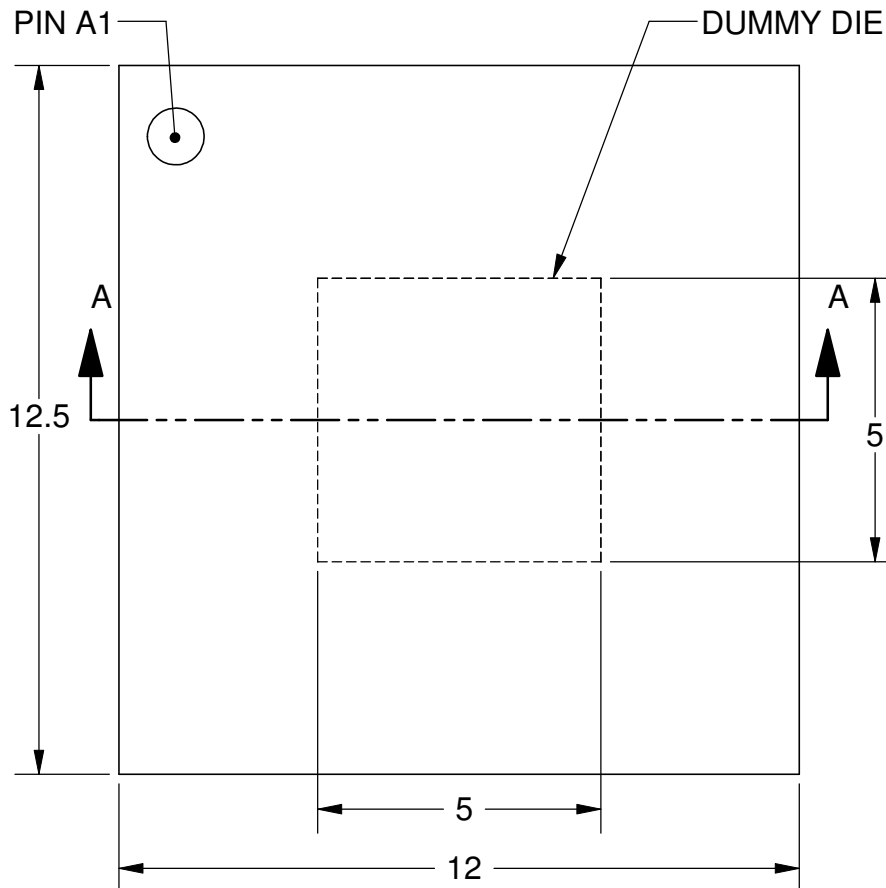
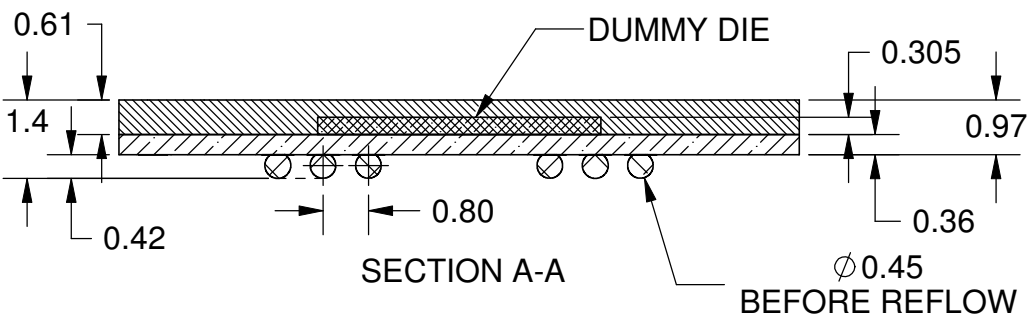
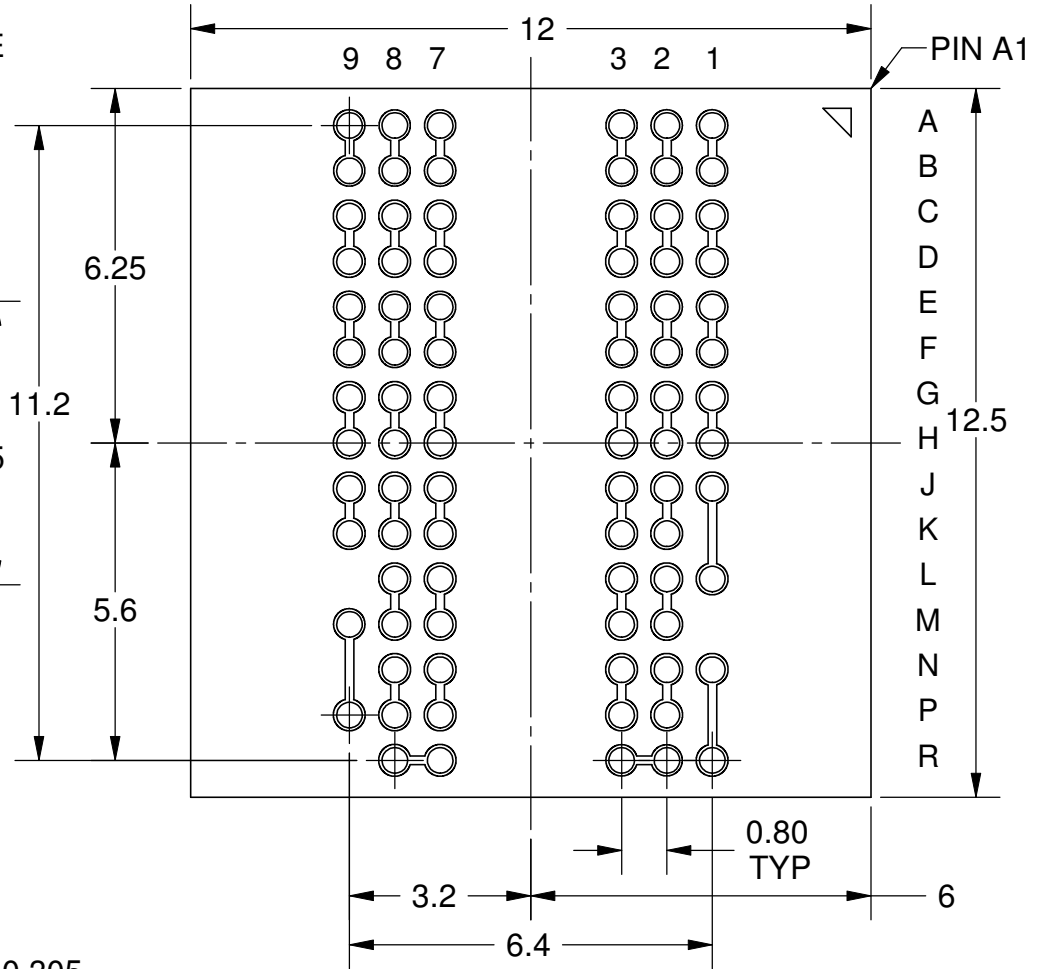


TOP VIEW



BALL VIEW



Notes: (Unless Otherwise Specified).

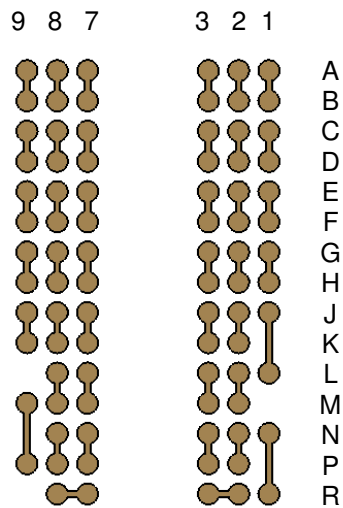
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.45mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.36mm (14 mil).
- 5) PAD Cu DIAMETER: 0.56mm (22 mil).
- 6) SUBSTRATE MATERIAL: FR4.
- 7) DUMMY DIE: 0.305mm (12 mil) THICK.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA84T.8C-DC655	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
BGA84T.8C-DC655D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA84T.8-DC655	Sn63/Pb37	NO	NO	NO
BGA84T.8-DC655D	Sn63/Pb37	NO	NO	YES

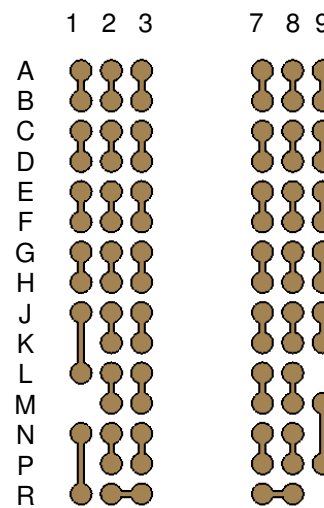
TOLERANCE UNLESS NOTED		APPROVALS		DATE	
X.X	+/- 0.1	DRAWN J. Hines		4/21/2011	
X.XX	+/- 0.05				
X.XXX	+/- 0.025				
ANGLES +/- 0.5°		ENG		TITLE	
ALL DIMENSIONS IN		MFG		BGA84T.8C-DC655D	
□ INCHES □ MILLIMETERS		QA		DAISY CHAIN DUMMY	
THIRD ANGLE PROJECTION		CUST		SCALE	SIZE
		REVISED		7.5:1	A
				DRAWING NO.	REV
				586650	A
				DO NOT SCALE DRAWING	
				SHEET 1 OF 2	

TopLine®

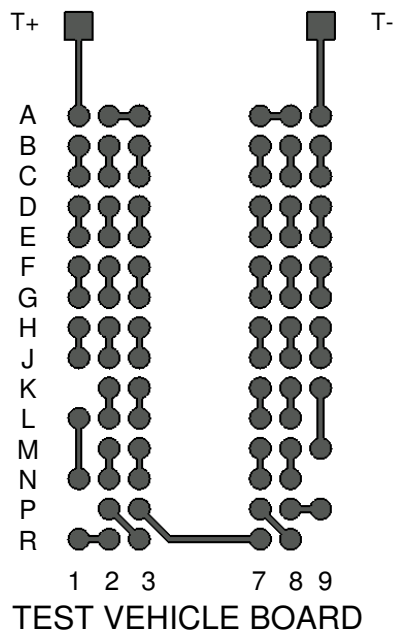
BALL VIEW



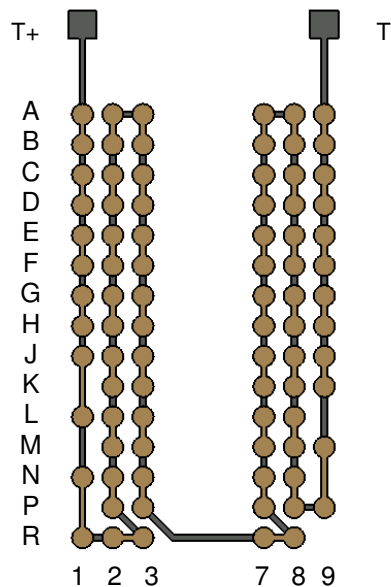
BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.56mm (22mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm (6mil).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.36mm (14mil).

TopLine ®			
TITLE		BGA84T.8C-DC655D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
5:1	A	586650	A
DO NOT SCALE DRAWING			SHEET 2 OF 2